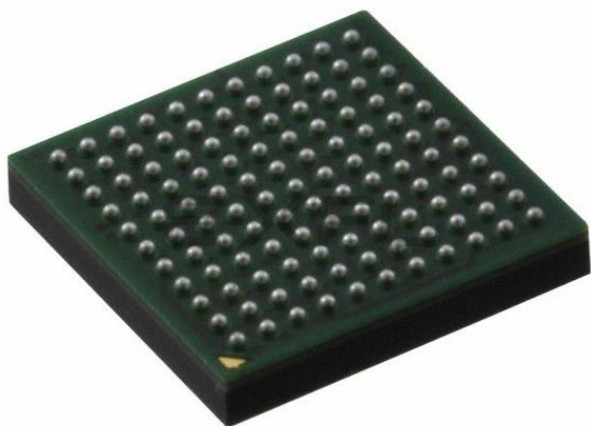




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Details

Product Status	Active
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	120MHz
Connectivity	CANbus, EBI/EMI, I ² C, IrDA, SD, SPI, UART/USART, USB, USB OTG
Peripherals	DMA, I ² S, LVD, POR, PWM, WDT
Number of I/O	83
Program Memory Size	1MB (1M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 3.6V
Data Converters	A/D 37x16b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	121-XFBGA
Supplier Device Package	121-XFBGA (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mk24fn1m0vdc12r

General

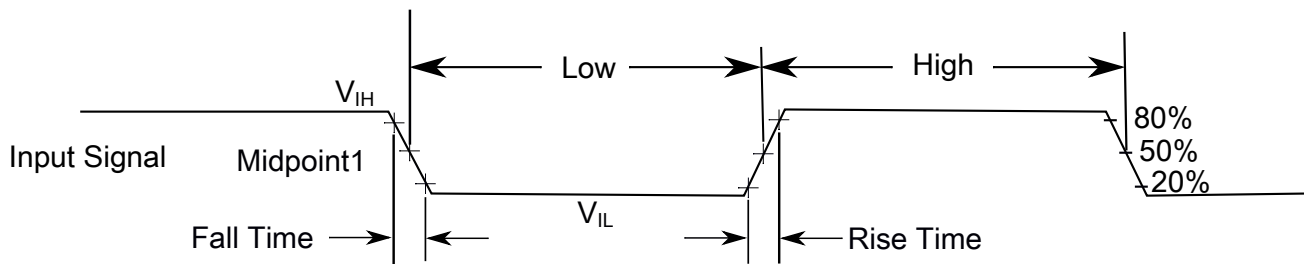
Symbol	Description	Min.	Max.	Unit
V_{DD}	Digital supply voltage	-0.3	3.8	V
I_{DD}	Digital supply current	—	185	mA
V_{DIO}	Digital input voltage (except RESET, EXTAL, and XTAL)	-0.3	5.5	V
V_{DRTC_WAKEUP}	RTC Wakeup input voltage	-0.3	$V_{BAT} + 0.3$	V
V_{AIO}	Analog ¹ , RESET, EXTAL, and XTAL input voltage	-0.3	$V_{DD} + 0.3$	V
I_D	Maximum current single pin limit (applies to all digital pins)	-25	25	mA
V_{DDA}	Analog supply voltage	$V_{DD} - 0.3$	$V_{DD} + 0.3$	V
V_{USB0_DP}	USB0_DP input voltage	-0.3	3.63	V
V_{USB0_DM}	USB0_DM input voltage	-0.3	3.63	V
V_{REGIN}	USB regulator input	-0.3	6.0	V
V_{BAT}	RTC battery supply voltage	-0.3	3.8	V

1. Analog pins are defined as pins that do not have an associated general purpose I/O port function.

2 General

2.1 AC electrical characteristics

Unless otherwise specified, propagation delays are measured from the 50% to the 50% point, and rise and fall times are measured at the 20% and 80% points, as shown in the following figure.



The midpoint is $V_{IL} + (V_{IH} - V_{IL}) / 2$

Figure 2. Input signal measurement reference

2.2 Nonswitching electrical specifications

Table 4. Voltage and current operating behaviors (continued)

Symbol	Description	Min.	Max.	Unit	Notes
	• $2.7\text{ V} \leq V_{DD} \leq 3.6\text{ V}$, $I_{OH} = -8\text{mA}$ • $1.71\text{ V} \leq V_{DD} \leq 2.7\text{ V}$, $I_{OH} = -3\text{mA}$	$V_{DD} - 0.5$	—	V	
		$V_{DD} - 0.5$	—	V	
	Output high voltage — low drive strength				
	• $2.7\text{ V} \leq V_{DD} \leq 3.6\text{ V}$, $I_{OH} = -2\text{mA}$ • $1.71\text{ V} \leq V_{DD} \leq 2.7\text{ V}$, $I_{OH} = -0.6\text{mA}$	$V_{DD} - 0.5$	—	V	
		$V_{DD} - 0.5$	—	V	
I_{OHT}	Output high current total for all ports	—	100	mA	
$V_{OH_RTC_WAKEUP}$	Output high voltage — high drive strength	$V_{BAT} - 0.5$	—	V	
	• $2.7\text{ V} \leq V_{BAT} \leq 3.6\text{ V}$, $I_{OH} = -10\text{mA}$ • $1.71\text{ V} \leq V_{BAT} \leq 2.7\text{ V}$, $I_{OH} = -3\text{mA}$	$V_{BAT} - 0.5$	—	V	
	Output high voltage — low drive strength	$V_{BAT} - 0.5$	—	V	
	• $2.7\text{ V} \leq V_{BAT} \leq 3.6\text{ V}$, $I_{OH} = -2\text{mA}$ • $1.71\text{ V} \leq V_{BAT} \leq 2.7\text{ V}$, $I_{OH} = -0.6\text{mA}$	$V_{BAT} - 0.5$	—	V	
$I_{OH_RTC_WAKEUP}$	Output high current total for RTC_WAKEUP pins	—	100	mA	
V_{OL}	Output low voltage — high drive strength				
	• $2.7\text{ V} \leq V_{DD} \leq 3.6\text{ V}$, $I_{OL} = 9\text{mA}$ • $1.71\text{ V} \leq V_{DD} \leq 2.7\text{ V}$, $I_{OL} = 3\text{mA}$	—	0.5	V	
		—	0.5	V	
	Output low voltage — low drive strength				
	• $2.7\text{ V} \leq V_{DD} \leq 3.6\text{ V}$, $I_{OL} = 2\text{mA}$ • $1.71\text{ V} \leq V_{DD} \leq 2.7\text{ V}$, $I_{OL} = 0.6\text{mA}$	—	0.5	V	
		—	0.5	V	
I_{OLT}	Output low current total for all ports	—	100	mA	
$V_{OL_RTC_WAKEUP}$	Output low voltage — high drive strength	—	0.5	V	
	• $2.7\text{ V} \leq V_{BAT} \leq 3.6\text{ V}$, $I_{OL} = 10\text{mA}$ • $1.71\text{ V} \leq V_{BAT} \leq 2.7\text{ V}$, $I_{OL} = 3\text{mA}$	—	0.5	V	
	Output low voltage — low drive strength	—	0.5	V	
	• $2.7\text{ V} \leq V_{BAT} \leq 3.6\text{ V}$, $I_{OL} = 2\text{mA}$ • $1.71\text{ V} \leq V_{BAT} \leq 2.7\text{ V}$, $I_{OL} = 0.6\text{mA}$	—	0.5	V	
$I_{OL_RTC_WAKEUP}$	Output low current total for RTC_WAKEUP pins	—	100	mA	
I_{IN}	Input leakage current (per pin) for full temperature range	—	1	μA	1
I_{IN}	Input leakage current (per pin) at 25°C	—	0.025	μA	1
$I_{IN_RTC_WAKEUP}$	Input leakage current (per RTC_WAKEUP pin) for full temperature range	—	1	μA	
$I_{IN_RTC_WAKEUP}$	Input leakage current (per RTC_WAKEUP pin) at 25°C	—	0.025	μA	

Table continues on the next page...

Table 4. Voltage and current operating behaviors (continued)

Symbol	Description	Min.	Max.	Unit	Notes
I_{OZ}	Hi-Z (off-state) leakage current (per pin)	—	0.25	μA	
$I_{OZ_RTC_WAKEUP}$	Hi-Z (off-state) leakage current (per RTC_WAKEUP pin)	—	0.25	μA	
R_{PU}	Internal pullup resistors (except RTC_WAKEUP pins)	20	50	$k\Omega$	2
R_{PD}	Internal pulldown resistors (except RTC_WAKEUP pins)	20	50	$k\Omega$	3

1. Measured at $V_{DD}=3.6V$

2. Measured at V_{DD} supply voltage = V_{DD} min and $V_{input} = V_{SS}$

3. Measured at V_{DD} supply voltage = V_{DD} min and $V_{input} = V_{DD}$

2.2.4 Power mode transition operating behaviors

All specifications except t_{POR} , and $VLLSx \rightarrow RUN$ recovery times in the following table assume this clock configuration:

- CPU and system clocks = 100 MHz
- Bus clock = 50 MHz
- FlexBus clock = 50 MHz
- Flash clock = 25 MHz

Table 5. Power mode transition operating behaviors

Symbol	Description	Min.	Max.	Unit	Notes
t_{POR}	After a POR event, amount of time from the point V_{DD} reaches 1.71 V to execution of the first instruction across the operating temperature range of the chip.	—	300	μs	
	• $VLLS0 \rightarrow RUN$	—	156	μs	
	• $VLLS1 \rightarrow RUN$	—	156	μs	
	• $VLLS2 \rightarrow RUN$	—	78	μs	
	• $VLLS3 \rightarrow RUN$	—	78	μs	
	• $LLS \rightarrow RUN$	—	4.8	μs	
	• $VLPS \rightarrow RUN$	—	4.5	μs	
	• $STOP \rightarrow RUN$	—	4.5	μs	

General

- Maximum T_A can be exceeded only if the user ensures that T_J does not exceed maximum T_J . The simplest method to determine T_J is:

$$T_J = T_A + R_{\theta JA} \times \text{chip power dissipation}$$

2.4.2 Thermal attributes

Table 13. Thermal attributes

Board type	Symbol	Description	144 LQFP	121 XFBGA	100 LQFP	Unit	Notes
Single-layer (1s)	$R_{\theta JA}$	Thermal resistance, junction to ambient (natural convection)	51	33.3	51	°C/W	1
Four-layer (2s2p)	$R_{\theta JA}$	Thermal resistance, junction to ambient (natural convection)	43	21.1	39	°C/W	1
Single-layer (1s)	$R_{\theta JMA}$	Thermal resistance, junction to ambient (200 ft./min. air speed)	42	26.2	41	°C/W	1
Four-layer (2s2p)	$R_{\theta JMA}$	Thermal resistance, junction to ambient (200 ft./min. air speed)	36	17.8	32	°C/W	1
—	$R_{\theta JB}$	Thermal resistance, junction to board	30	16.3	24	°C/W	2
—	$R_{\theta JC}$	Thermal resistance, junction to case	11	12	11	°C/W	3
—	Ψ_{JT}	Thermal characterization parameter, junction to package top outside center (natural convection)	2	0.2	2	°C/W	4

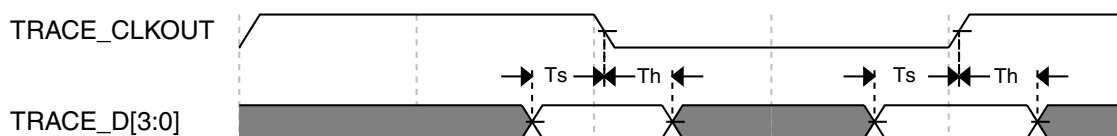


Figure 6. Trace data specifications

3.1.2 JTAG electricals

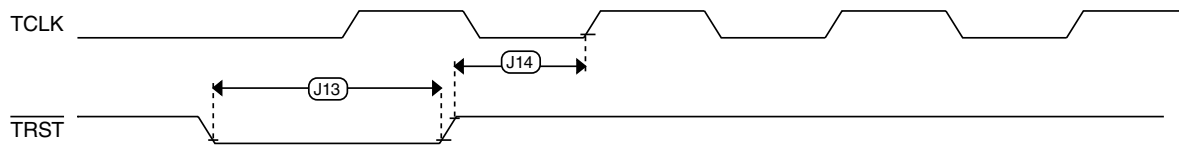
Table 15. JTAG limited voltage range electricals

Symbol	Description	Min.	Max.	Unit
	Operating voltage	2.7	3.6	V
J1	TCLK frequency of operation - Boundary Scan - JTAG and CJTAG - Serial Wire Debug	0 0 0	10 25 50	MHz
J2	TCLK cycle period	1/J1	—	ns
J3	TCLK clock pulse width - Boundary Scan - JTAG and CJTAG - Serial Wire Debug	50 20 10	— — —	ns ns ns
J4	TCLK rise and fall times	—	3	ns
J5	Boundary scan input data setup time to TCLK rise	20	—	ns
J6	Boundary scan input data hold time after TCLK rise	2.6	—	ns
J7	TCLK low to boundary scan output data valid	—	25	ns
J8	TCLK low to boundary scan output high-Z	—	25	ns
J9	TMS, TDI input data setup time to TCLK rise	8	—	ns
J10	TMS, TDI input data hold time after TCLK rise	1	—	ns
J11	TCLK low to TDO data valid	—	17	ns
J12	TCLK low to TDO high-Z	—	17	ns
J13	$\overline{\text{TRST}}$ assert time	100	—	ns
J14	$\overline{\text{TRST}}$ setup time (negation) to TCLK high	8	—	ns

Table 16. JTAG full voltage range electricals

Symbol	Description	Min.	Max.	Unit
	Operating voltage	1.71	3.6	V

Table continues on the next page...

Figure 10. $\overline{\text{TRST}}$ timing

3.2 System modules

There are no specifications necessary for the device's system modules.

3.3 Clock modules

3.3.1 MCG specifications

Table 17. MCG specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
$f_{\text{ints_ft}}$	Internal reference frequency (slow clock) — factory trimmed at nominal VDD and 25 °C	—	32.768	—	kHz	
$f_{\text{ints_t}}$	Internal reference frequency (slow clock) — user trimmed	31.25	—	39.0625	kHz	
I_{ints}	Internal reference (slow clock) current	—	20	—	μA	
$\Delta f_{\text{dco_res_t}}$	Resolution of trimmed average DCO output frequency at fixed voltage and temperature — using SCTRIM and SCFTRIM	—	± 0.3	± 0.6	$\%f_{\text{dco}}$	1
$\Delta f_{\text{dco_res_t}}$	Resolution of trimmed average DCO output frequency at fixed voltage and temperature — using SCTRIM only	—	± 0.2	± 0.5	$\%f_{\text{dco}}$	1
$\Delta f_{\text{dco_t}}$	Total deviation of trimmed average DCO output frequency over voltage and temperature	—	± 0.5	± 2	$\%f_{\text{dco}}$	1, 2
$\Delta f_{\text{dco_t}}$	Total deviation of trimmed average DCO output frequency over fixed voltage and temperature range of 0–70°C	—	± 0.3	± 1	$\%f_{\text{dco}}$	1
$f_{\text{intf_ft}}$	Internal reference frequency (fast clock) — factory trimmed at nominal VDD and 25°C	—	4	—	MHz	
$f_{\text{intf_t}}$	Internal reference frequency (fast clock) — user trimmed at nominal VDD and 25 °C	3	—	5	MHz	
I_{intf}	Internal reference (fast clock) current	—	25	—	μA	

Table continues on the next page...

3.3.3.2 Oscillator frequency specifications

Table 20. Oscillator frequency specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
f_{osc_lo}	Oscillator crystal or resonator frequency — low-frequency mode (MCG_C2[RANGE]=00)	32	—	40	kHz	
$f_{osc_hi_1}$	Oscillator crystal or resonator frequency — high-frequency mode (low range) (MCG_C2[RANGE]=01)	3	—	8	MHz	
$f_{osc_hi_2}$	Oscillator crystal or resonator frequency — high-frequency mode (high range) (MCG_C2[RANGE]=1x)	8	—	32	MHz	
f_{ec_extal}	Input clock frequency (external clock mode)	—	—	50	MHz	1, 2
t_{dc_extal}	Input clock duty cycle (external clock mode)	40	50	60	%	
t_{cst}	Crystal startup time — 32 kHz low-frequency, low-power mode (HGO=0)	—	750	—	ms	3, 4
	Crystal startup time — 32 kHz low-frequency, high-gain mode (HGO=1)	—	250	—	ms	
	Crystal startup time — 8 MHz high-frequency (MCG_C2[RANGE]=01), low-power mode (HGO=0)	—	0.6	—	ms	
	Crystal startup time — 8 MHz high-frequency (MCG_C2[RANGE]=01), high-gain mode (HGO=1)	—	1	—	ms	

1. Other frequency limits may apply when external clock is being used as a reference for the FLL
2. When transitioning from FEI or FBI to FBE mode, restrict the frequency of the input clock so that, when it is divided by FRDIV, it remains within the limits of the DCO input clock frequency.
3. Proper PC board layout procedures must be followed to achieve specifications.
4. Crystal startup time is defined as the time between the oscillator being enabled and the OSCINIT bit in the MCG_S register being set.

NOTE

The 32 kHz oscillator works in low power mode by default and cannot be moved into high power/gain mode.

3.3.4 32 kHz oscillator electrical characteristics

3.3.4.1 32 kHz oscillator DC electrical specifications

Table 21. 32kHz oscillator DC electrical specifications

Symbol	Description	Min.	Typ.	Max.	Unit
V_{BAT}	Supply voltage	1.71	—	3.6	V
R_F	Internal feedback resistor	—	100	—	MΩ

Table continues on the next page...

3.4.1.4 Reliability specifications

Table 26. NVM reliability specifications

Symbol	Description	Min.	Typ. ¹	Max.	Unit	Notes
Program Flash						
$t_{\text{nvmretp10k}}$	Data retention after up to 10 K cycles	5	50	—	years	
$t_{\text{nvmretp1k}}$	Data retention after up to 1 K cycles	20	100	—	years	
n_{nvmcycp}	Cycling endurance	10 K	50 K	—	cycles	²

1. Typical data retention values are based on measured response accelerated at high temperature and derated to a constant 25°C use profile. Engineering Bulletin EB618 does not apply to this technology. Typical endurance defined in Engineering Bulletin EB619.
2. Cycling endurance represents number of program/erase cycles at $-40^{\circ}\text{C} \leq T_j \leq 125^{\circ}\text{C}$.

3.4.2 EzPort switching specifications

Table 27. EzPort switching specifications

Num	Description	Min.	Max.	Unit
	Operating voltage	1.71	3.6	V
EP1	EZP_CK frequency of operation (all commands except READ)	—	$f_{\text{SYS}}/2$	MHz
EP1a	EZP_CK frequency of operation (READ command)	—	$f_{\text{SYS}}/8$	MHz
EP2	$\overline{\text{EZP_CS}}$ negation to next EZP_CS assertion	$2 \times t_{\text{EZP_CK}}$	—	ns
EP3	$\overline{\text{EZP_CS}}$ input valid to EZP_CK high (setup)	5	—	ns
EP4	EZP_CK high to $\overline{\text{EZP_CS}}$ input invalid (hold)	5	—	ns
EP5	EZP_D input valid to EZP_CK high (setup)	2	—	ns
EP6	EZP_CK high to EZP_D input invalid (hold)	5	—	ns
EP7	EZP_CK low to EZP_Q output valid	—	18	ns
EP8	EZP_CK low to EZP_Q output invalid (hold)	0	—	ns
EP9	$\overline{\text{EZP_CS}}$ negation to EZP_Q tri-state	—	12	ns

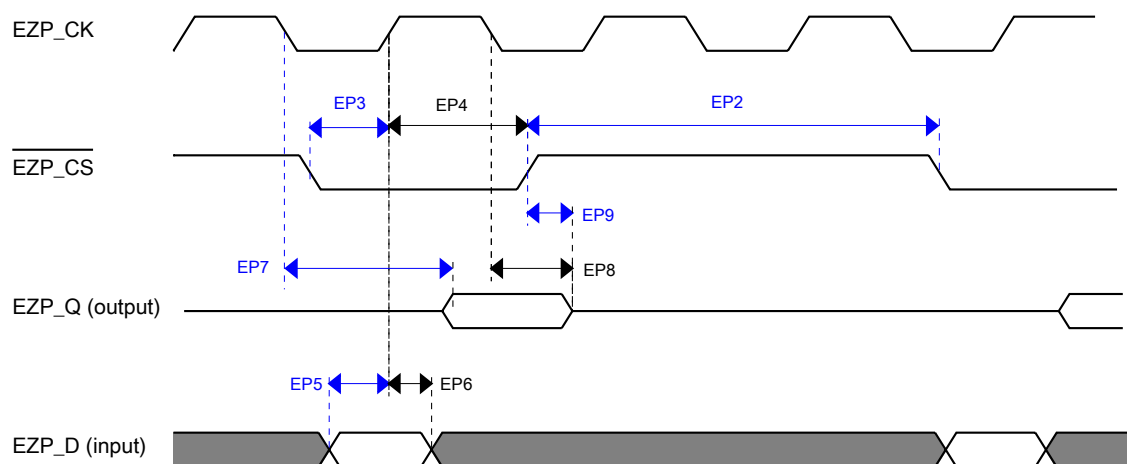


Figure 11. EzPort Timing Diagram

3.4.3 Flexbus switching specifications

All processor bus timings are synchronous; input setup/hold and output delay are given in respect to the rising edge of a reference clock, FB_CLK. The FB_CLK frequency may be the same as the internal system bus frequency or an integer divider of that frequency.

The following timing numbers indicate when data is latched or driven onto the external bus, relative to the Flexbus output clock (FB_CLK). All other timing relationships can be derived from these values.

Table 28. Flexbus limited voltage range switching specifications

Num	Description	Min.	Max.	Unit	Notes
	Operating voltage	2.7	3.6	V	
	Frequency of operation	—	FB_CLK	MHz	
FB1	Clock period	20	—	ns	
FB2	Address, data, and control output valid	—	11.5	ns	1
FB3	Address, data, and control output hold	0.5	—	ns	1
FB4	Data and $\overline{\text{FB_TA}}$ input setup	8.5	—	ns	2
FB5	Data and $\overline{\text{FB_TA}}$ input hold	0.5	—	ns	2

1. Specification is valid for all FB_AD[31:0], $\overline{\text{FB_BE/BWE}}$, $\overline{\text{FB_CS}}$, $\overline{\text{FB_OE}}$, FB_R/W, $\overline{\text{FB_TBST}}$, FB_TSIZ[1:0], FB_ALE, and FB_TS.

3.6.3.2 12-bit DAC operating behaviors

Table 34. 12-bit DAC operating behaviors

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
I_{DDA_DACLP}	Supply current — low-power mode	—	—	150	μA	
I_{DDA_DACHP}	Supply current — high-speed mode	—	—	700	μA	
t_{DACLP}	Full-scale settling time (0x080 to 0xF7F) — low-power mode	—	100	200	μs	1
t_{DACHP}	Full-scale settling time (0x080 to 0xF7F) — high-power mode	—	15	30	μs	1
$t_{CCDACLP}$	Code-to-code settling time (0xBF8 to 0xC08) — low-power mode and high-speed mode	—	0.7	1	μs	1
$V_{dacoutl}$	DAC output voltage range low — high-speed mode, no load, DAC set to 0x000	—	—	100	mV	
$V_{dacouth}$	DAC output voltage range high — high-speed mode, no load, DAC set to 0xFFFF	$V_{DACR} - 100$	—	V_{DACR}	mV	
INL	Integral non-linearity error — high speed mode	—	—	± 8	LSB	2
DNL	Differential non-linearity error — $V_{DACR} > 2 V$	—	—	± 1	LSB	3
DNL	Differential non-linearity error — $V_{DACR} = V_{REF_OUT}$	—	—	± 1	LSB	4
V_{OFFSET}	Offset error	—	± 0.4	± 0.8	%FSR	5
E_G	Gain error	—	± 0.1	± 0.6	%FSR	5
PSRR	Power supply rejection ratio, $V_{DDA} \geq 2.4 V$	60	—	90	dB	
T_{CO}	Temperature coefficient offset voltage	—	3.7	—	$\mu V/C$	6
T_{GE}	Temperature coefficient gain error	—	0.000421	—	%FSR/C	
A_C	Offset aging coefficient	—	—	100	$\mu V/yr$	
R_{op}	Output resistance (load = 3 k Ω)	—	—	250	Ω	
SR	Slew rate -80h $\rightarrow$ F7Fh $\rightarrow$ 80h - High power (SP_{HP}) - Low power (SP_{LP})	1.2 0.05	1.7 0.12	— —	V/ μs	
CT	Channel to channel cross talk	—	—	-80	dB	
BW	3dB bandwidth - High power (SP_{HP}) - Low power (SP_{LP})	550 40	— —	— —	kHz	

1. Settling within ± 1 LSB
2. The INL is measured for 0 + 100 mV to $V_{DACR} - 100$ mV
3. The DNL is measured for 0 + 100 mV to $V_{DACR} - 100$ mV
4. The DNL is measured for 0 + 100 mV to $V_{DACR} - 100$ mV with $V_{DDA} > 2.4 V$
5. Calculated by a best fit curve from $V_{SS} + 100$ mV to $V_{DACR} - 100$ mV

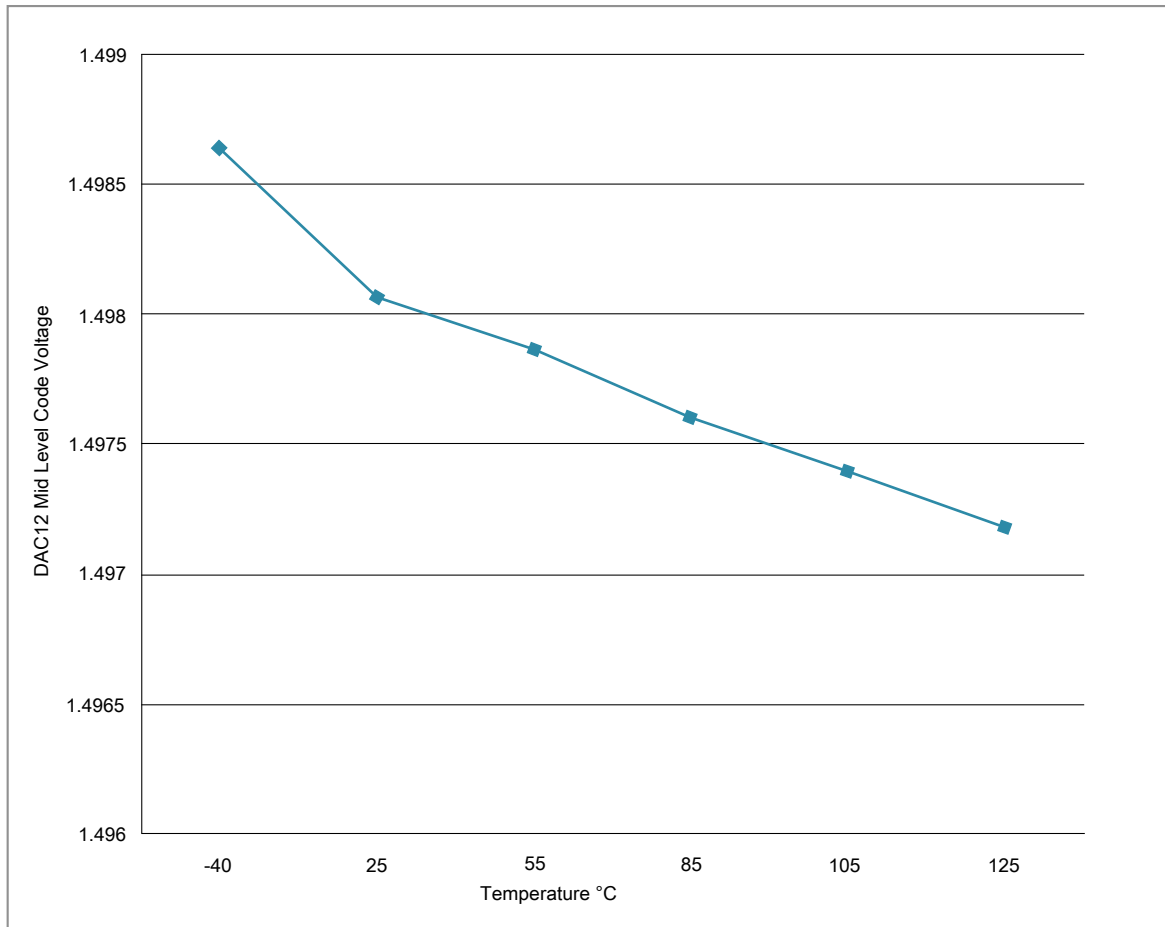


Figure 20. Offset at half scale vs. temperature

3.6.4 Voltage reference electrical specifications

Table 35. VREF full-range operating requirements

Symbol	Description	Min.	Max.	Unit	Notes
V_{DDA}	Supply voltage	1.71	3.6	V	—
T_A	Temperature	Operating temperature range of the device		°C	—
C_L	Output load capacitance	100		nF	1, 2

1. C_L must be connected to VREF_OUT if the VREF_OUT functionality is being used for either an internal or external reference.
2. The load capacitance should not exceed +/-25% of the nominal specified C_L value over the operating temperature range of the device.

3.8.1 USB electrical specifications

The USB electricals for the USB On-the-Go module conform to the standards documented by the Universal Serial Bus Implementers Forum. For the most up-to-date standards, visit usb.org.

NOTE

The MCGPLLCLK meets the USB jitter and signaling rate specifications for certification with the use of an external clock/crystal for both Device and Host modes.

The MCGFLLCLK does not meet the USB jitter or signaling rate specifications for certification.

The IRC48M meets the USB jitter and signaling rate specifications for certification in Device mode when the USB clock recovery mode is enabled. It does not meet the USB signaling rate specifications for certification in Host mode operation.

3.8.2 USB DCD electrical specifications

Table 39. USB0 DCD electrical specifications

Symbol	Description	Min.	Typ.	Max.	Unit
V _{DP_SRC}	USB_DP source voltage (up to 250 μ A)	0.5	—	0.7	V
V _{LGC}	Threshold voltage for logic high	0.8	—	2.0	V
I _{DP_SRC}	USB_DP source current	7	10	13	μ A
I _{DM_SINK}	USB_DM sink current	50	100	150	μ A
R _{DM_DWN}	D- pulldown resistance for data pin contact detect	14.25	—	24.8	k Ω
V _{DAT_REF}	Data detect voltage	0.25	0.33	0.4	V

3.8.3 USB VREG electrical specifications

Table 40. USB VREG electrical specifications

Symbol	Description	Min.	Typ. ¹	Max.	Unit	Notes
VREGIN	Input supply voltage	2.7	—	5.5	V	

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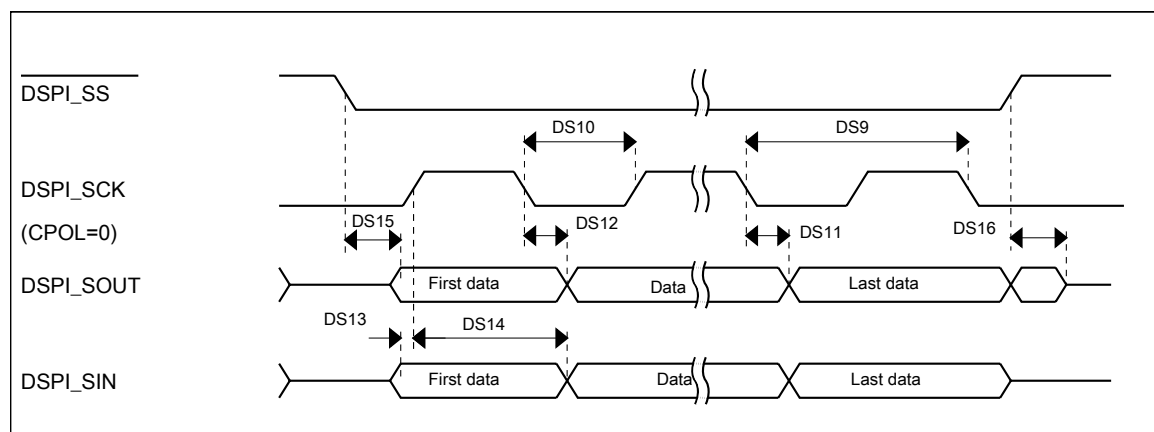


Figure 24. DSPI classic SPI timing — slave mode

3.8.7 Inter-Integrated Circuit Interface (I²C) timing

Table 45. I²C timing

Characteristic	Symbol	Standard Mode		Fast Mode		Unit
		Minimum	Maximum	Minimum	Maximum	
SCL Clock Frequency	f _{SCL}	0	100	0	400 ¹	kHz
Hold time (repeated) START condition. After this period, the first clock pulse is generated.	t _{HD} ; STA	4	—	0.6	—	μs
LOW period of the SCL clock	t _{LOW}	4.7	—	1.25	—	μs
HIGH period of the SCL clock	t _{HIGH}	4	—	0.6	—	μs
Set-up time for a repeated START condition	t _{SU} ; STA	4.7	—	0.6	—	μs
Data hold time for I ² C bus devices	t _{HD} ; DAT	0 ²	3.45 ³	0 ⁴	0.9 ²	μs
Data set-up time	t _{SU} ; DAT	250 ⁵	—	100 ^{3, 6}	—	ns
Rise time of SDA and SCL signals	t _r	—	1000	20 + 0.1C _b ⁷	300	ns
Fall time of SDA and SCL signals	t _f	—	300	20 + 0.1C _b ⁶	300	ns
Set-up time for STOP condition	t _{SU} ; STO	4	—	0.6	—	μs
Bus free time between STOP and START condition	t _{BUF}	4.7	—	1.3	—	μs
Pulse width of spikes that must be suppressed by the input filter	t _{SP}	N/A	N/A	0	50	ns

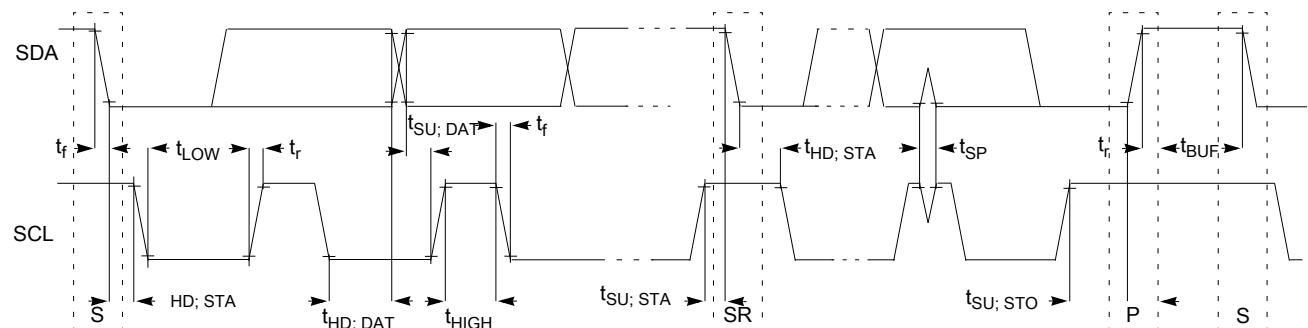
1. The maximum SCL Clock Frequency in Fast mode with maximum bus loading can only be achieved when using the High drive pins across the full voltage range and when using the Normal drive pins and VDD ≥ 2.7 V.
2. The master mode I²C deasserts ACK of an address byte simultaneously with the falling edge of SCL. If no slaves acknowledge this address byte, then a negative hold time can result, depending on the edge rates of the SDA and SCL lines.
3. The maximum t_{HD}; DAT must be met only if the device does not stretch the LOW period (t_{LOW}) of the SCL signal.
4. Input signal Slew = 10 ns and Output Load = 50 pF
5. Set-up time in slave-transmitter mode is 1 IPBus clock period, if the TX FIFO is empty.

6. A Fast mode I²C bus device can be used in a Standard mode I²C bus system, but the requirement $t_{\text{SU; DAT}} \geq 250$ ns must then be met. This is automatically the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, then it must output the next data bit to the SDA line $t_{\text{rmax}} + t_{\text{SU; DAT}} = 1000 + 250 = 1250$ ns (according to the Standard mode I²C bus specification) before the SCL line is released.
7. C_b = total capacitance of the one bus line in pF.

Table 46. I²C 1 Mbps timing

Characteristic	Symbol	Minimum	Maximum	Unit
SCL Clock Frequency	f_{SCL}	0	1 ¹	MHz
Hold time (repeated) START condition. After this period, the first clock pulse is generated.	$t_{\text{HD; STA}}$	0.26	—	μs
LOW period of the SCL clock	t_{LOW}	0.5	—	μs
HIGH period of the SCL clock	t_{HIGH}	0.26	—	μs
Set-up time for a repeated START condition	$t_{\text{SU; STA}}$	0.26	—	μs
Data hold time for I ² C bus devices	$t_{\text{HD; DAT}}$	0	—	μs
Data set-up time	$t_{\text{SU; DAT}}$	50	—	ns
Rise time of SDA and SCL signals	t_r	$20 + 0.1C_b$ ²	120	ns
Fall time of SDA and SCL signals	t_f	$20 + 0.1C_b$ ²	120	ns
Set-up time for STOP condition	$t_{\text{SU; STO}}$	0.26	—	μs
Bus free time between STOP and START condition	t_{BUF}	0.5	—	μs
Pulse width of spikes that must be suppressed by the input filter	t_{SP}	0	50	ns

1. The maximum SCL clock frequency of 1 Mbps can support maximum bus loading when using the High drive pins across the full voltage range.
2. C_b = total capacitance of the one bus line in pF.

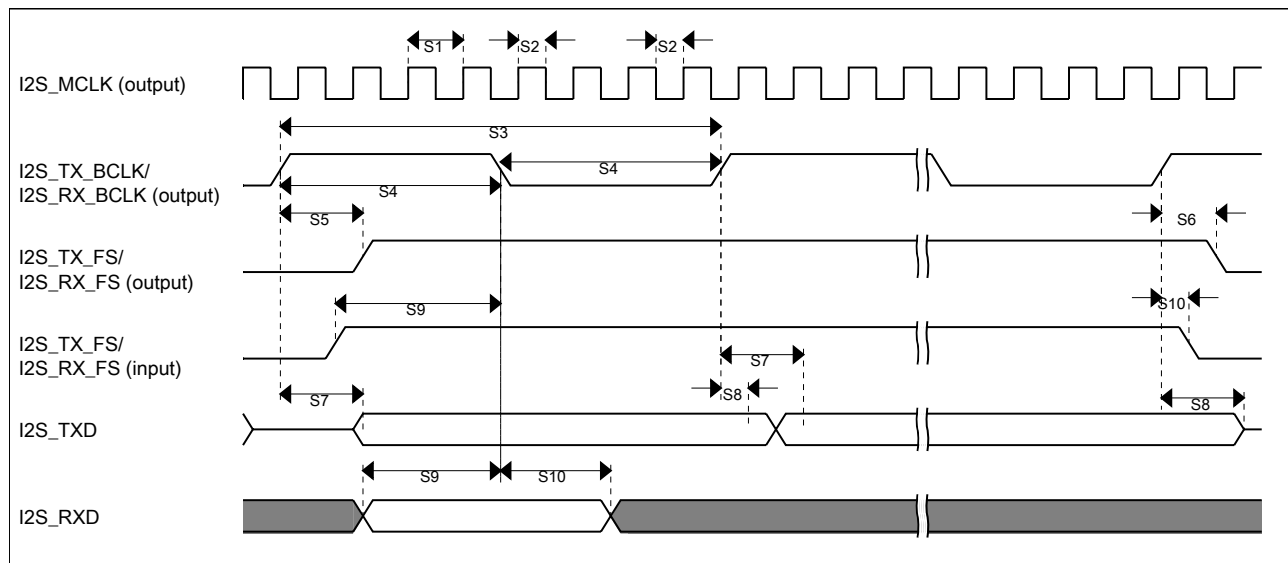
**Figure 25. Timing definition for devices on the I²C bus**

3.8.8 UART switching specifications

See [General switching specifications](#).

Table 50. I2S/SAI master mode timing (continued)

Num.	Characteristic	Min.	Max.	Unit
S3	I2S_TX_BCLK/I2S_RX_BCLK cycle time (output)	80	—	ns
S4	I2S_TX_BCLK/I2S_RX_BCLK pulse width high/low	45%	55%	BCLK period
S5	I2S_TX_BCLK/I2S_RX_BCLK to I2S_TX_FS/ I2S_RX_FS output valid	—	15	ns
S6	I2S_TX_BCLK/I2S_RX_BCLK to I2S_TX_FS/ I2S_RX_FS output invalid	-1	—	ns
S7	I2S_TX_BCLK to I2S_TXD valid	—	15	ns
S8	I2S_TX_BCLK to I2S_TXD invalid	0	—	ns
S9	I2S_RXD/I2S_RX_FS input setup before I2S_RX_BCLK	22.5	—	ns
S10	I2S_RXD/I2S_RX_FS input hold after I2S_RX_BCLK	0	—	ns

**Figure 29. I2S/SAI timing — master modes****Table 51. I2S/SAI slave mode timing**

Num.	Characteristic	Min.	Max.	Unit
	Operating voltage	1.71	3.6	V
S11	I2S_TX_BCLK/I2S_RX_BCLK cycle time (input)	80	—	ns
S12	I2S_TX_BCLK/I2S_RX_BCLK pulse width high/low (input)	45%	55%	MCLK period
S13	I2S_TX_FS/I2S_RX_FS input setup before I2S_TX_BCLK/I2S_RX_BCLK	7	—	ns
S14	I2S_TX_FS/I2S_RX_FS input hold after I2S_TX_BCLK/I2S_RX_BCLK	2	—	ns

Table continues on the next page...

Table 53. I2S/SAI slave mode timing in VLPR, VLPW, and VLPS modes (full voltage range) (continued)

Num.	Characteristic	Min.	Max.	Unit
S18	I2S_RXD hold after I2S_RX_BCLK	11	—	ns
S19	I2S_TX_FS input assertion to I2S_TXD output valid ¹	—	72	ns

1. Applies to first bit in each frame and only if the TCR4[FSE] bit is clear

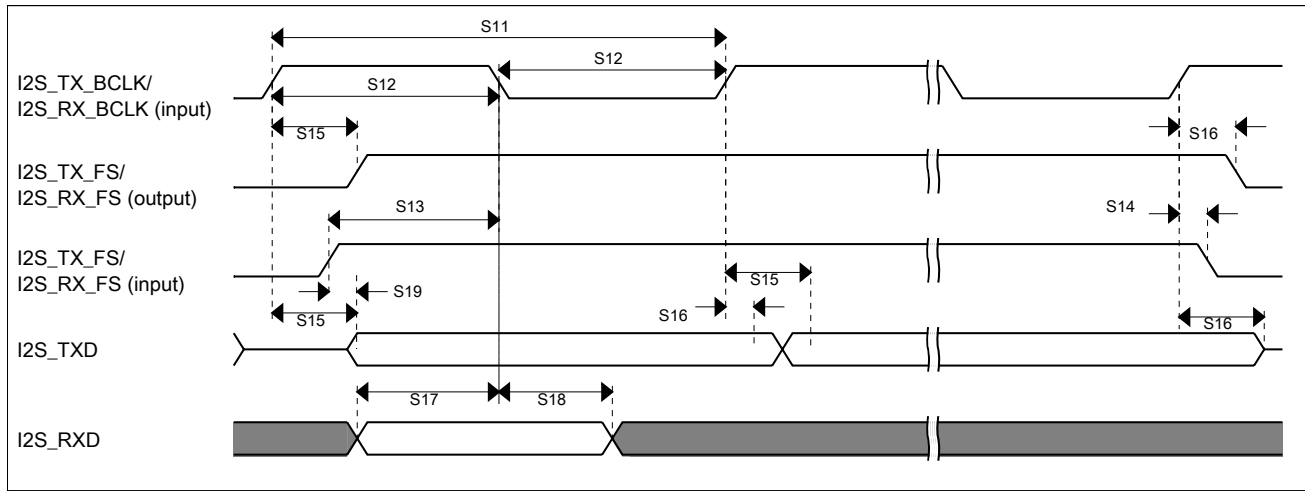


Figure 32. I2S/SAI timing — slave modes

4 Dimensions

4.1 Obtaining package dimensions

Package dimensions are provided in package drawings.

To find a package drawing, go to nxp.com and perform a keyword search for the drawing's document number:

If you want the drawing for this package	Then use this document number
100-pin LQFP	98ASS23308W
121-pin XFBGA	98ASA00595D
144-pin LQFP	98ASS23177W

144 QFP	100 LQFP	Pin Name	Default	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	ALT8	ALT9
68	46	DISABLED		PTA16	SPI0_SOUT	UART0_CTS_b/ UART0_COL_b	RMII0_TXD0/ MII0_TXD0		I2S0_RX_FS	I2S0_RXD1			
69	47	ADC1_SE17	ADC1_SE17	PTA17	SPI0_SIN	UART0_RTS_b	RMII0_TXD1/ MII0_TXD1		I2S0_MCLK				
70	48	VDD	VDD										
71	49	VSS	VSS										
72	50	EXTAL0	EXTAL0	PTA18		FTM0_FLT2	FTM_CLKIN0					EXTAL0	
73	51	XTAL0	XTAL0	PTA19		FTM1_FLT0	FTM_CLKIN1		LPTMR0_ALT1			LPTMR0_ALT1	
74	52	RESET_b	RESET_b									RESET_b	
75	—	DISABLED		PTA24			MII0_TXD2		FB_A29				
76	—	DISABLED		PTA25			MII0_TXCLK		FB_A28				
77	—	DISABLED		PTA26			MII0_TXD3		FB_A27				
78	—	DISABLED		PTA27			MII0_CRS		FB_A26				
79	—	DISABLED		PTA28			MII0_TXER		FB_A25				
80	—	DISABLED		PTA29			MII0_COL		FB_A24				
81	53	ADC0_SE8/ ADC1_SE8	ADC0_SE8/ ADC1_SE8	PTB0/ LLWU_P5	I2C0_SCL	FTM1_CH0	RMII0_MDIO/ MII0_MDIO		FTM1_QD_PHA			LLWU_P5	
82	54	ADC0_SE9/ ADC1_SE9	ADC0_SE9/ ADC1_SE9	PTB1	I2C0_SDA	FTM1_CH1	RMII0_MDC/ MII0_MDC		FTM1_QD_PHB				
83	55	ADC0_SE12	ADC0_SE12	PTB2	I2C0_SCL	UART0_RTS_b	ENET0_1588_TMR0		FTM0_FLT3				
84	56	ADC0_SE13	ADC0_SE13	PTB3	I2C0_SDA	UART0_CTS_b/ UART0_COL_b	ENET0_1588_TMR1		FTM0_FLT0				
85	—	ADC1_SE10	ADC1_SE10	PTB4			ENET0_1588_TMR2		FTM1_FLT0				
86	—	ADC1_SE11	ADC1_SE11	PTB5			ENET0_1588_TMR3		FTM2_FLT0				
87	—	ADC1_SE12	ADC1_SE12	PTB6				FB_AD23					
88	—	ADC1_SE13	ADC1_SE13	PTB7				FB_AD22					
89	—	DISABLED		PTB8		UART3_RTS_b		FB_AD21					

Pinout

144 QFP	100 LQFP	Pin Name	Default	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	ALT8	ALT9
						UART0_COL_b							
133	99	ADC0_SE7b	ADC0_SE7b	PTD6/LLWU_P15	SPI0_PCS3	UART0_RX	FTM0_CH6	FB_AD0	FTM0_FLT0	SPI1_SOUT		LLWU_P15	
134	—	VSS	VSS										
135	—	VDD	VDD										

5.2 Unused analog interfaces

Table 54. Unused analog interfaces

Module name	Pins	Recommendation if unused
ADC	ADC0_DP1, ADC0_DM1, ADC1_DP1, ADC1_DM1, ADC0_DP0/ADC1_DP3, ADC0_DM0/ADC1_DM3, ADC1_DP0/ADC0_DP3, ADC1_DM0/ADC0_DM3, ADC1_SE16/ADC0_SE22, ADC0_SE16/ADC0_SE21, ADC1_SE18	Ground
DAC ¹	DAC0_OUT, DAC1_OUT	Float
USB	VREGIN, USB0_GND, VOUT33 ²	Connect VREGIN and VOUT33 together and tie to ground through a 10 kΩ resistor. Do not tie directly to ground, as this causes a latch-up risk.
	USB0_DM, USB0_DP	Float

1. Unused DAC signals do not apply to all parts. See the [Pinout](#) section for details.

2. USB0_VBUS and USB0_GND are board level signals

5.3 K24 Pinouts

The below figure shows the pinout diagram for the devices supported by this document. Many signals may be multiplexed onto a single pin. To determine what signals can be used on which pin, see the previous section.

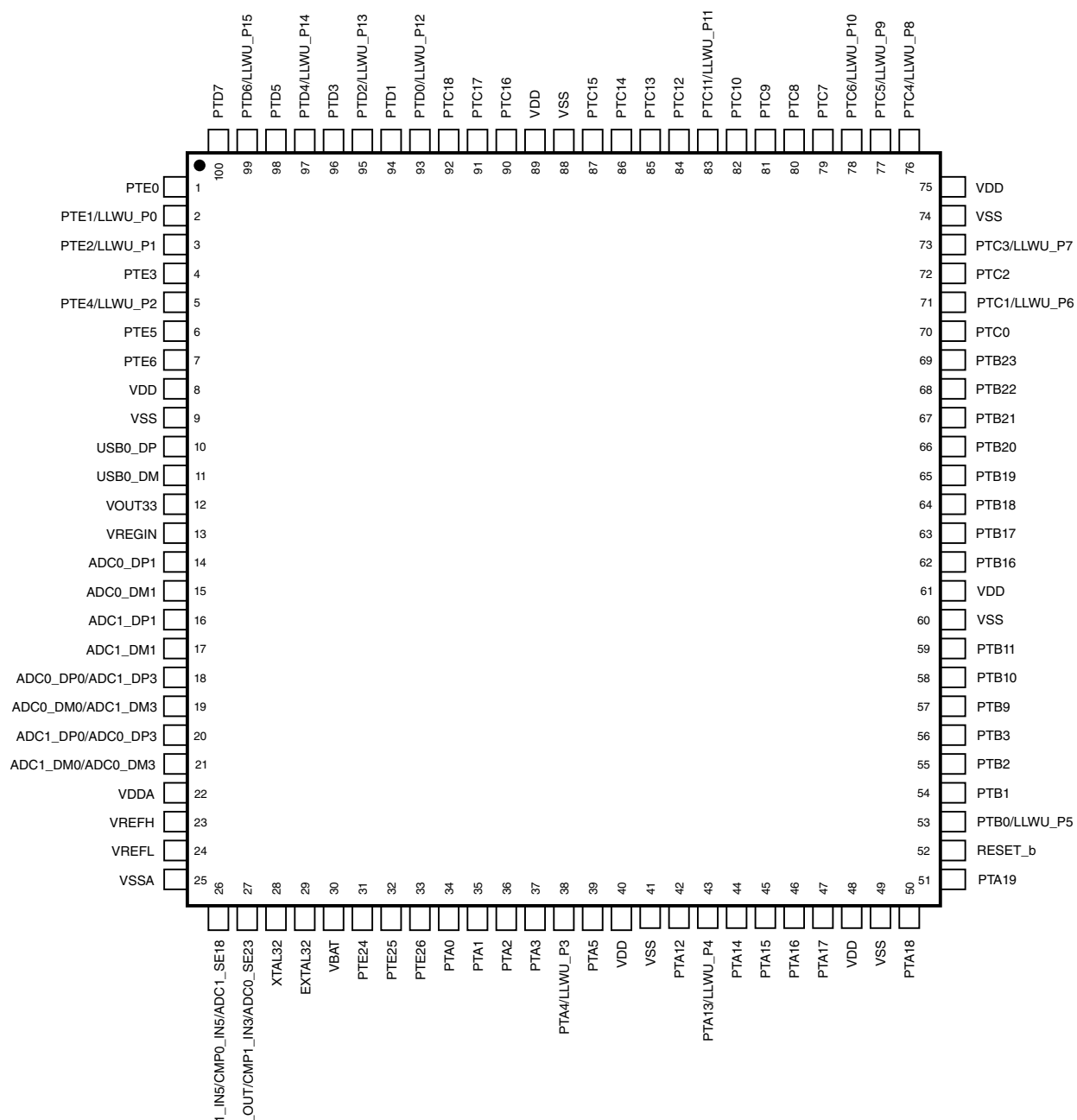


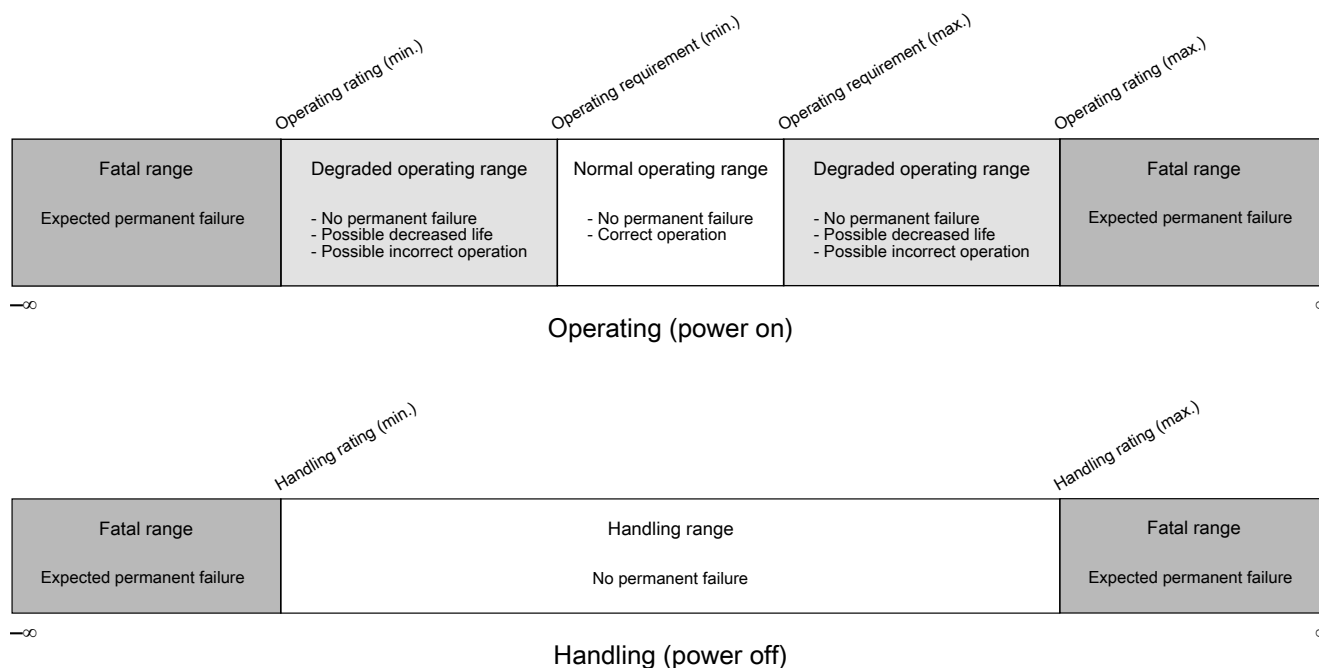
Figure 35. 100 LQFP Pinout Diagram

8.3 Typical-value conditions

Typical values assume you meet the following conditions (or other conditions as specified):

Symbol	Description	Value	Unit
T_A	Ambient temperature	25	°C
V_{DD}	Supply voltage	3.3	V

8.4 Relationship between ratings and operating requirements



8.5 Guidelines for ratings and operating requirements

Follow these guidelines for ratings and operating requirements:

- Never exceed any of the chip's ratings.
- During normal operation, don't exceed any of the chip's operating requirements.
- If you must exceed an operating requirement at times other than during normal operation (for example, during power sequencing), limit the duration as much as possible.